Specification of Thermoelectric Module TEFC1-00208P

Description

The 2 couples, 1.0 mm × 1.6mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 72 °C, designed for superior cooling and heating up to 100/200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	72	81	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	0.26	0.28	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	0.8	0.8	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	0.13	0.14	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	0.22	0.24	The module resistance is tested under AC	
Tolerance (%)	10%		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters

0.07 typ O.07 typ Bottom Ceramics *Reversed polarity is available WB posts can be provided by request

Manufacturing Options

A. Solder:

B. Sealant:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217° C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt = 240° C)

3. EPS: Epoxy sealant

C. Ceramics:

D. Ceramics Surface Options:

1. Alumina (Al₂O₃, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

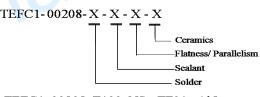
2. Metalized

Ordering Option

Suffix	Thickness	Flatness/	Lead wire length(mm)
	H (mm)	Parallelism (mm)	Standard/Optional length
TF	$0:1.1 \pm 0.1$	0: 0.03/0.03	Available on request
TF	$1:1.1 \pm 0.03$	1: 0.015/0.015	Available on request

Eg. TF01: Thickness 1.1 ± 0.1 (mm) and Flatness 0.015/0.015 (mm)

Naming for the Module



TEFC1-00208-T100-NS-TF01-AlO T100: Solder, BiSn (Melting Point=138 ℃)

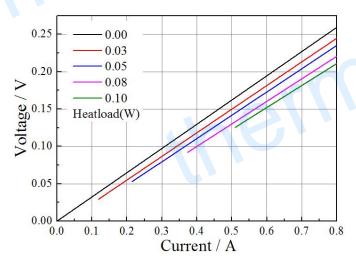
NS: No sealing AlO: Alumina white 96%

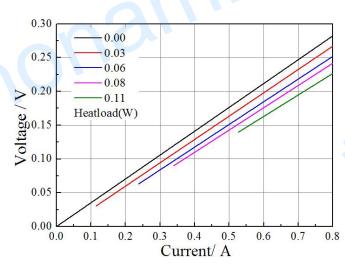
Specification of Thermoelectric Module

TEFC1-00208P

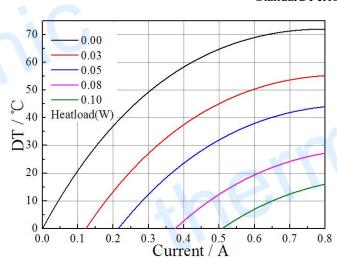
Performance Curves at Th=27 °C

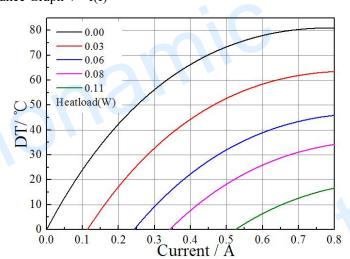
Performance Curves at Th=50 °C





Standard Performance Graph V = f(I)





Standard Performance Graph $\Delta T = f(I)$

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC